Title (en)

INTEGRATED CHEMICAL MECHANICAL POLISHING COMPOSITION AND PROCESS FOR SINGLE PLATEN PROCESSING

Title (de)

ZUSAMMENSETZUNG ZUM INTEGRIERTEN CHEMISCH-MECHANISCHEN POLIEREN UND VERFAHREN ZUR EINZELPLATTENBEHANDLUNG

Title (fr)

COMPOSITION DE POLISSAGE CHIMICO-MECANIQUE INTEGRE ET PROCEDE POUR TRAITER UNE PLATINE INDIVIDUELLE

Publication

**EP 1899111 A2 20080319 (EN)**

Application

**EP 06772376 A 20060606**

Priority

- US 2006022037 W 20060606
- US 68772105 P 20050606

Abstract (en)

[origin: WO2006133249A2] Chemical mechanical polishing (CMP) compositions and single CMP platen process for the removal of copper and barrier layer material from a microelectronic device substrate having same thereon. The process includes the in situ transformation of a Step I slurry formulation, which is used to selectively remove and planarize copper, into a Step II slurry formulation, which is used to selectively remove barrier layer material, on a single CMP platen pad.

IPC 8 full level

**B44C 1/22** (2006.01); **C23F 1/00** (2006.01); **C23F 1/10** (2006.01); **H01L 21/302** (2006.01)

CPC (source: EP KR US)

**B24B 37/00** (2013.01 - KR); **C09G 1/02** (2013.01 - EP KR US); **C09K 3/14** (2013.01 - KR); **C09K 3/1463** (2013.01 - EP US); **C09K 3/1472** (2013.01 - EP US); **H01L 21/321** (2013.01 - KR); **H01L 21/3212** (2013.01 - EP US)

Citation (search report)

See references of WO 2006133249A2

Designated contracting state (EPC)

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Designated extension state (EPC)

AL BA HR MK RS

DOCDB simple family (publication)

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